

RoHS Compliant Product

A suffix of "-C" specifies halogen & lead-free

## N-Channel SOT-323

### MAXIMUM RATINGS

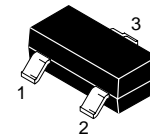
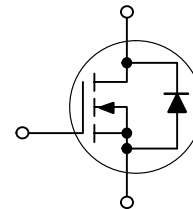
Rating	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	Vdc
Drain-Gate Voltage (R <sub>GS</sub> = 1.0 MΩ)	V <sub>DGR</sub>	60	Vdc
Drain Current - Continuous T <sub>C</sub> = 25°C (Note 1.) T <sub>C</sub> = 100°C (Note 1.) - Pulsed (Note 2.)	I <sub>D</sub> I <sub>D</sub> I <sub>DM</sub>	±115 ±75 ±800	mAdc
Gate-Source Voltage - Continuous - Non-repetitive (t <sub>p</sub> ≤ 50 μs)	V <sub>GS</sub> V <sub>GSM</sub>	±20 ±40	Vdc Vpk

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 3.) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 4.) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

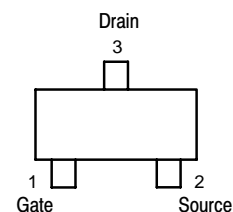
1. The Power Dissipation of the package may result in a lower continuous drain current.
2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
3. FR-5 = 1.0 x 0.75 x 0.062 in.
4. Alumina = 0.4 x 0.3 x 0.025 in 99.5% alumina.

N-Channel



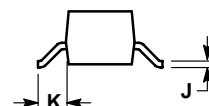
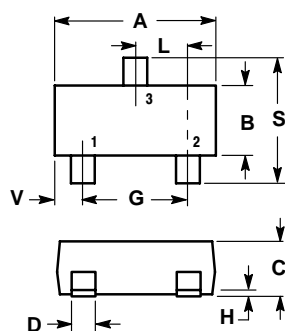
SOT-323

### MARKING DIAGRAM & PIN ASSIGNMENT



K72 , 702 = Device Code

SOT-323		
Dim	Min	Max
A	1.800	2.200
B	1.150	1.350
C	0.800	1.000
D	0.300	0.400
G	1.200	1.400
H	0.000	0.100
J	0.100	0.250
K	0.350	0.500
L	0.590	0.720
S	2.000	2.400
V	0.280	0.420
All Dimension in mm		



**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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**OFF CHARACTERISTICS**

Drain-Source Breakdown Voltage ( $V_{GS} = 0, I_D = 10 \mu\text{Adc}$ )	$V_{(BR)DSS}$	60	-	-	Vdc
Zero Gate Voltage Drain Current ( $V_{GS} = 0, V_{DS} = 60 \text{ Vdc}$ )	$I_{DSS}$	-	-	1.0 500	$\mu\text{Adc}$
Gate-Body Leakage Current, Forward ( $V_{GS} = 20 \text{ Vdc}$ )	$I_{GSSF}$	-	-	100	nAdc
Gate-Body Leakage Current, Reverse ( $V_{GS} = -20 \text{ Vdc}$ )	$I_{GSSR}$	-	-	-100	nAdc

**ON CHARACTERISTICS** (Note 2.)

Gate Threshold Voltage ( $V_{DS} = V_{GS}, I_D = 250 \mu\text{Adc}$ )	$V_{GS(th)}$	1.0	-	2.5	Vdc
On-State Drain Current ( $V_{DS} \geq 2.0 V_{DS(on)}, V_{GS} = 10 \text{ Vdc}$ )	$I_{D(on)}$	500	-	-	mA
Static Drain-Source On-State Voltage ( $V_{GS} = 10 \text{ Vdc}, I_D = 500 \text{ mAdc}$ ) ( $V_{GS} = 5.0 \text{ Vdc}, I_D = 50 \text{ mAdc}$ )	$V_{DS(on)}$	-	-	3.75 0.375	Vdc
Static Drain-Source On-State Resistance ( $V_{GS} = 10 \text{ V}, I_D = 500 \text{ mAdc}$ ) $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$ ( $V_{GS} = 5.0 \text{ Vdc}, I_D = 50 \text{ mAdc}$ ) $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	$r_{DS(on)}$	-	-	7.5 13.5 7.5 13.5	Ohms
Forward Transconductance ( $V_{DS} \geq 2.0 V_{DS(on)}, I_D = 200 \text{ mAdc}$ )	$g_{FS}$	80	-	-	mmhos

**DYNAMIC CHARACTERISTICS**

Input Capacitance ( $V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz}$ )	$C_{iss}$	-	-	50	pF
Output Capacitance ( $V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz}$ )	$C_{oss}$	-	-	25	pF
Reverse Transfer Capacitance ( $V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz}$ )	$C_{rss}$	-	-	5.0	pF

**SWITCHING CHARACTERISTICS** (Note 2.)

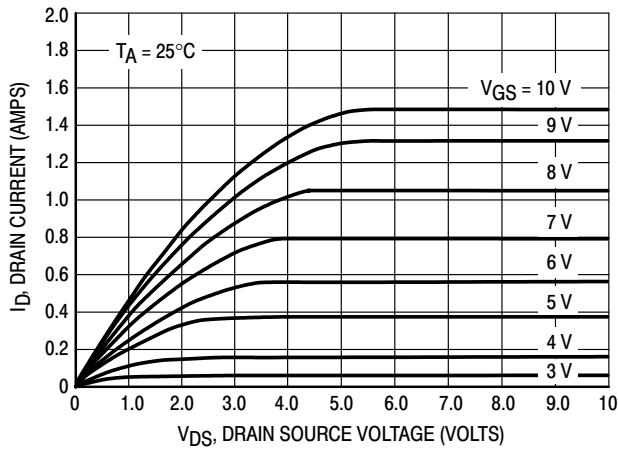
Turn-On Delay Time	$(V_{DD} = 25 \text{ Vdc}, I_D \cong 500 \text{ mAdc}, R_G = 25 \Omega, R_L = 50 \Omega, V_{gen} = 10 \text{ V})$	$t_{d(on)}$	-	-	20	ns
Turn-Off Delay Time		$t_{d(off)}$	-	-	40	ns

**BODY-DRAIN DIODE RATINGS**

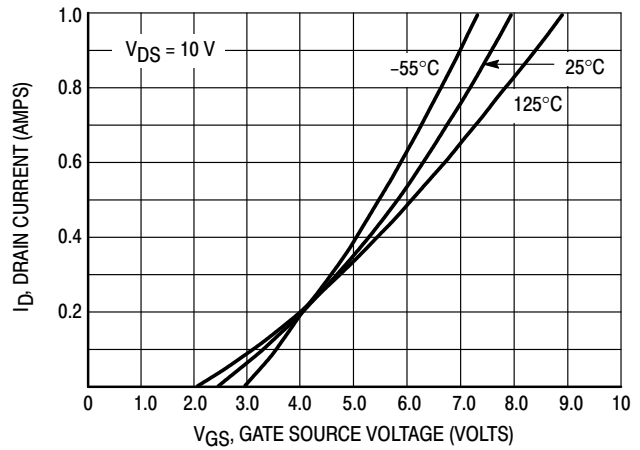
Diode Forward On-Voltage ( $I_S = 11.5 \text{ mAdc}, V_{GS} = 0 \text{ V}$ )	$V_{SD}$	-	-	-1.5	Vdc
Source Current Continuous (Body Diode)	$I_S$	-	-	-115	mAdc
Source Current Pulsed	$I_{SM}$	-	-	-800	mAdc

2. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

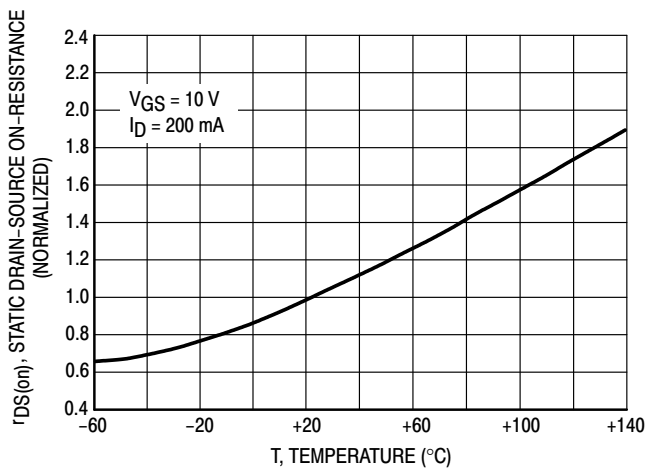
**TYPICAL ELECTRICAL CHARACTERISTICS**



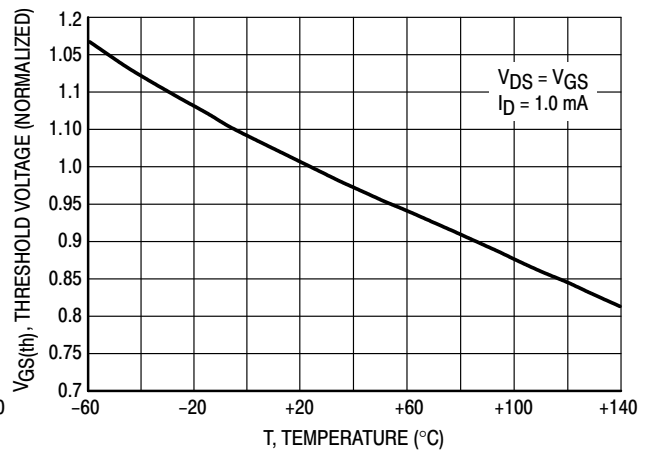
**Figure 1. Ohmic Region**



**Figure 2. Transfer Characteristics**



**Figure 3. Temperature versus Static Drain-Source On-Resistance**



**Figure 4. Temperature versus Gate Threshold Voltage**